

Title (en)  
RESIN COMPOSITION AND MOLDED ARTICLE

Title (de)  
HARZZUSAMMENSETZUNG UND FORMARTIKEL

Title (fr)  
COMPOSITION DE RÉSINE ET ARTICLE MOULÉ

Publication  
**EP 3527621 A4 20200624 (EN)**

Application  
**EP 17860263 A 20171011**

Priority  
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Abstract (en)  
[origin: EP3527621A1] The purpose of the present invention is to provide a polyester resin composition which exhibits excellent shock resistance, tensile strength, modulus of elasticity, and molding properties. This resin composition contains 50-95 parts by mass of a polyester resin (A), 0.5-10 parts by mass of an oxidized olefin wax (B), and 5-40 parts by mass of an inorganic filler (C), wherein (A) satisfies (A-1) and (A-2), and (B) satisfies (B-1) and (B-2). (A-1) Containing a constituent unit (a1) derived from an aromatic dicarboxylic acid, and a constituent unit (a2) derived from a C2-10 diol. (A-2) The melting point (Tm) according to DSC being in the range of 200-245°C. (B-1) The weight-average molecular weight calculated in terms of polystyrene measured according to GPC being 8,000-20,000. (B-2) Being an oxidized modified product of a homopolymer or copolymer of at least one type selected from ethylene and C3-12  $\alpha$ -olefin.

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• [YA] US 2014128504 A1 20140508 - LU BING [US]  
• [YA] EP 2048199 A1 20090415 - MITSUBISHI ENG PLASTICS CORP [JP]  
• See references of WO 2018070425A1

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